

10030104_CLS

Most Frequently Occurring Classifications of Patents Returned
From A Search of 10030104 on August 05, 2003

Original Classifications

4 382/147
2 324/158.1
2 324/537
2 324/754
2 324/758
2 361/792

Cross-Reference Classifications

5 257/E23.067
5 348/126
4 257/698
4 324/754
3 257/700
3 257/E23.069
3 324/537
3 356/237.5
3 382/147
3 382/151
2 174/261
2 257/693
2 257/737
2 257/E23.004
2 257/E23.068
2 324/158.1
2 324/757
2 324/758
2 324/765
2 324/95
2 356/394
2 356/398
2 361/777

Combined Classifications

7 382/147
6 324/754
5 257/E23.067
5 324/537
5 348/126
4 257/698
4 324/158.1
4 324/758
3 174/261
3 257/693

10030104_CLS

3 257/700
3 257/E23.069
3 324/765
3 356/237.5
3 356/394
3 382/151
2 174/260
2 250/559.34
2 257/737
2 257/E23.004
2 257/E23.068
2 324/757
2 324/95
2 356/398
2 361/777
2 361/792

10030104_CLSTITLES

Titles of Most Frequently Occurring Classifications of Patents Returned

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7 382/147 (4 OR, 3 XR)
 Class 382 : IMAGE ANALYSIS
 382/100 APPLICATIONS
 382/141 .Manufacturing or product inspection
 382/145 ..Inspection of semiconductor device or printed
 circuit board
 382/147 ...Inspecting printed circuit boards

6 324/754 (2 OR, 4 XR)
 Class 324 : ELECTRICITY: MEASURING AND TESTING
 324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
 ELECTRIC COMPONENTS
 324/537 .Of individual circuit component or element
 324/754 ..With probe elements

5 257/E23.067 (0 OR, 5 XR)
 Class 257 : ACTIVE SOLID-STATE DEVICES
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
 SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
 257/E23.01 .Arrangements for conducting electric current
 to or from solid-state body in operation
 , e.g., leads,
 terminal arrangements (EPO)
 257/E23.023 ..Consisting of soldered or bonded
 constructions (EPO)
 257/E23.06 ...Leads, i.e., metallizations or lead-frames
 on insulating substrates, e.g., chip carriers (EPO)
 257/E23.067Via connections through substrates, e.g.,
 pins going through substrate, coaxial cables (EPO)

5 324/537 (2 OR, 3 XR)
 Class 324 : ELECTRICITY: MEASURING AND TESTING
 324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
 ELECTRIC COMPONENTS
 324/537 .Of individual circuit component or element

5 348/126 (0 OR, 5 XR)
 Class 348 : TELEVISION
 348/61 SPECIAL APPLICATIONS

10030104_CLSTITLES

348/125 .Flaw detector
348/126 ..Of electronic circuit chip or board

4 257/698 (0 OR, 4 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/688 .With large area flexible electrodes in press
contact with opposite sides of active sem

iconductor chip

and surrounded by an insulating element,

e.g., ring

257/690 .With contact or lead

257/698 ..With specific electrical feedthrough
structure

4 324/158.1 (2 OR, 2 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING

324/158.1 MISCELLANEOUS

4 324/758 (2 OR, 2 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING

324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
ELECTRIC COMPONENTS

324/537 .Of individual circuit component or element

324/754 ..With probe elements

324/758 ...Probe alignment or positioning

3 174/261 (1 OR, 2 XR)

Class 174 : ELECTRICITY: CONDUCTORS AND INSULATORS

174/68.1 CONDUITS, CABLES OR CONDUCTORS

174/250 .Preformed panel circuit arrangement (e.g.,
printed circuit)

174/261 ..With particular conductive connection (e.g.,
crossover)

3 257/693 (1 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/688 .With large area flexible electrodes in press
contact with opposite sides of active se

miconductor chip

and surrounded by an insulating element,

e.g., ring

257/690 .With contact or lead

257/692 ..With particular lead geometry

257/693 ...External connection to housing

3 257/700 (0 OR, 3 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/688 .With large area flexible electrodes in press

10030104_CLSTITLES

iconductor chip
 contact with opposite sides of active sem
 and surrounded by an insulating element,
 e.g., ring
 257/690 .With contact or lead
 257/700 ..Multiple contact layers separated from each
 other by insulator means and forming part o
 f a package or
 housing (e.g., plural ceramic layer package
)

3 257/E23.069 (0 OR, 3 XR)
 Class 257 : ACTIVE SOLID-STATE DEVICES
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
 SEMICONDUCTOR OR OTHER SOLID-STATE DEV
 ICES (EPO)
 257/E23.01 .Arrangements for conducting electric current
 to or from solid-state body in operatio
 n, e.g., leads,
 terminal arrangements (EPO)
 257/E23.023 ..Consisting of soldered or bonded
 constructions (EPO)
 257/E23.06 ...Leads, i.e., metallizations or lead-frames
 on insulating substrates, e.g., chip carr
 iers (EPO)
 257/E23.068Additional leads joined to metallizations
 on insulating substrate, e.g., pins, bumps
 , wires, flat
 leads (EPO)
 257/E23.069Spherical bumps on substrate for external
 connection, e.g., ball grid arrays (BGA) (E
 PO)

3 324/765 (1 OR, 2 XR)
 Class 324 : ELECTRICITY: MEASURING AND TESTING
 324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
 ELECTRIC COMPONENTS
 324/537 .Of individual circuit component or element
 324/765 ..Test of semiconductor device

3 356/237.5 (0 OR, 3 XR)
 Class 356 : OPTICS: MEASURING AND TESTING
 356/237.1 INSPECTION OF FLAWS OR IMPURITIES
 356/237.2 ..Surface condition
 356/237.5 ..On patterned or topographical surface (e.g.,
 wafer, mask, circuit board)

3 356/394 (1 OR, 2 XR)

10030104 CLSTITLES

Class 356 : OPTICS: MEASURING AND TESTING
 356/388 BY CONFIGURATION COMPARISON
 356/394 .With comparison to master, desired shape, or
 reference voltage

3 382/151 (0 OR, 3 XR)
 Class 382 : IMAGE ANALYSIS
 382/100 APPLICATIONS
 382/141 .Manufacturing or product inspection
 382/145 ..Inspection of semiconductor device or printe

d

circuit board
 382/151 ...Alignment, registration, or position
 determination

2 174/260 (1 OR, 1 XR)
 Class 174 : ELECTRICITY: CONDUCTORS AND INSULATORS
 174/68.1 CONDUITS, CABLES OR CONDUCTORS
 174/250 .Preformed panel circuit arrangement (e.g.,
 printed circuit)
 174/260 ..With electrical device

2 250/559.34 (1 OR, 1 XR)
 Class 250 : RADIANT ENERGY
 250/200 PHOTOCELLS; CIRCUITS AND APPARATUS
 250/559.01 .With circuit for evaluating a web, strand,
 strip, or sheet
 250/559.29 ..Measuring position
 250/559.34 ...Lead or wire bond inspection

2 257/737 (0 OR, 2 XR)
 Class 257 : ACTIVE SOLID-STATE DEVICES
 257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
 257/737 .Bump leads

2 257/E23.004 (0 OR, 2 XR)
 Class 257 : ACTIVE SOLID-STATE DEVICES
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
 SEMICONDUCTOR OR OTHER SOLID-STATE DEVICE

S (EPO)

257/E23.003 .Mountings, e.g., nondetachable insulating
 substrates (EPO)
 257/E23.004 ..Characterized by shape (EPO)

2 257/E23.068 (0 OR, 2 XR)
 Class 257 : ACTIVE SOLID-STATE DEVICES
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR
 SEMICONDUCTOR OR OTHER SOLID-STATE DEVI

10030104_CLSTITLES

CES (EPO)

257/E23.01 .Arrangements for conducting electric current
to or from solid-state body in operation
, e.g., leads,
terminal arrangements (EPO)
257/E23.023 ..Consisting of soldered or bonded
constructions (EPO)
257/E23.06Leads, i.e., metallizations or lead-frames
on insulating substrates, e.g., chip carri
ers (EPO)
257/E23.068Additional leads joined to metallizations
on insulating substrate, e.g., pins, bumps,
wires, flat
leads (EPO)

2 324/757 (0 OR, 2 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING
324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
ELECTRIC COMPONENTS
324/537 .Of individual circuit component or element
324/754 ..With probe elements
324/757 ...Probe contact enhancement

2 324/95 (0 OR, 2 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING
324/76.11 MEASURING, TESTING, OR SENSING ELECTRICITY, PE

R

SE
324/95 .With waveguide or long line

2 356/398 (0, OR, 2 XR)

Class 356 : OPTICS: MEASURING AND TESTING
356/388 BY CONFIGURATION COMPARISON
356/398 .With object being compared and light beam
moved relative to each other (e.g., scannin

g)

2 361/777 (0 OR, 2 XR)

Class 361 : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES
361/600 HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE
ELECTRICAL COMPONENTS
361/679 .For electronic systems and devices
361/748 ..Printed circuit board
361/760 ...Connection of components to board
361/777By specific pattern on board

2 361/792 (2 OR, 0 XR)

10030104 CLSTITLES

Class 361 : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES

361/600 . HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE
ELECTRICAL COMPONENTS

361/679 .For electronic systems and devices

361/748 ..Printed circuit board

361/784 ...Plural

361/792Plural contiguous boards